

STM32WL_QFN48_HP_DirectTie_RefBoard

MB1789_HP

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Sheet 1: Project overview (this page)

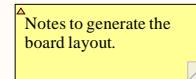
Sheet 2: MB1789_HPP.SchDoc

Legend

General comment such as function title, configuration, ...

Text to be added to silkscreen.

Warning text.



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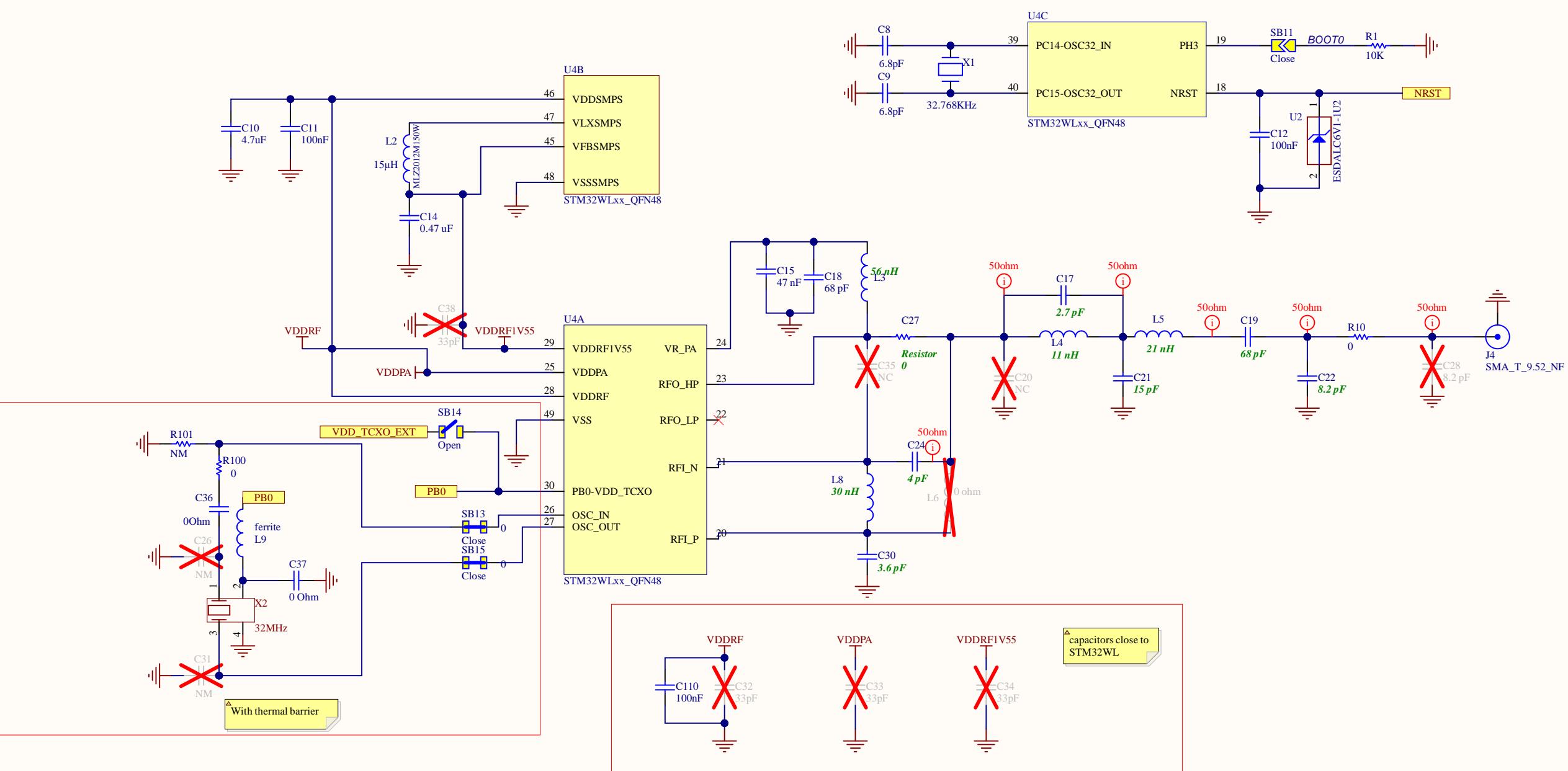
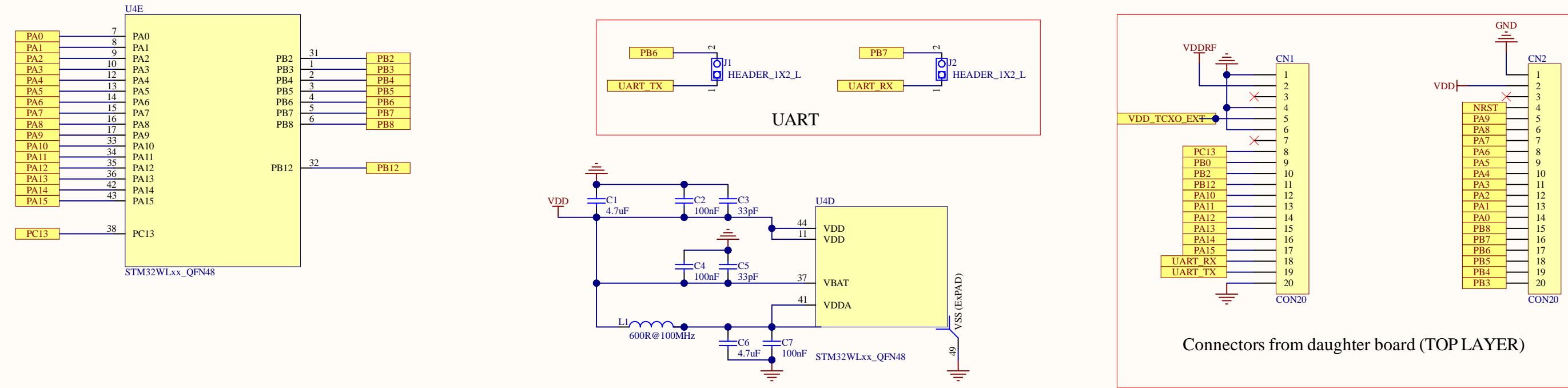
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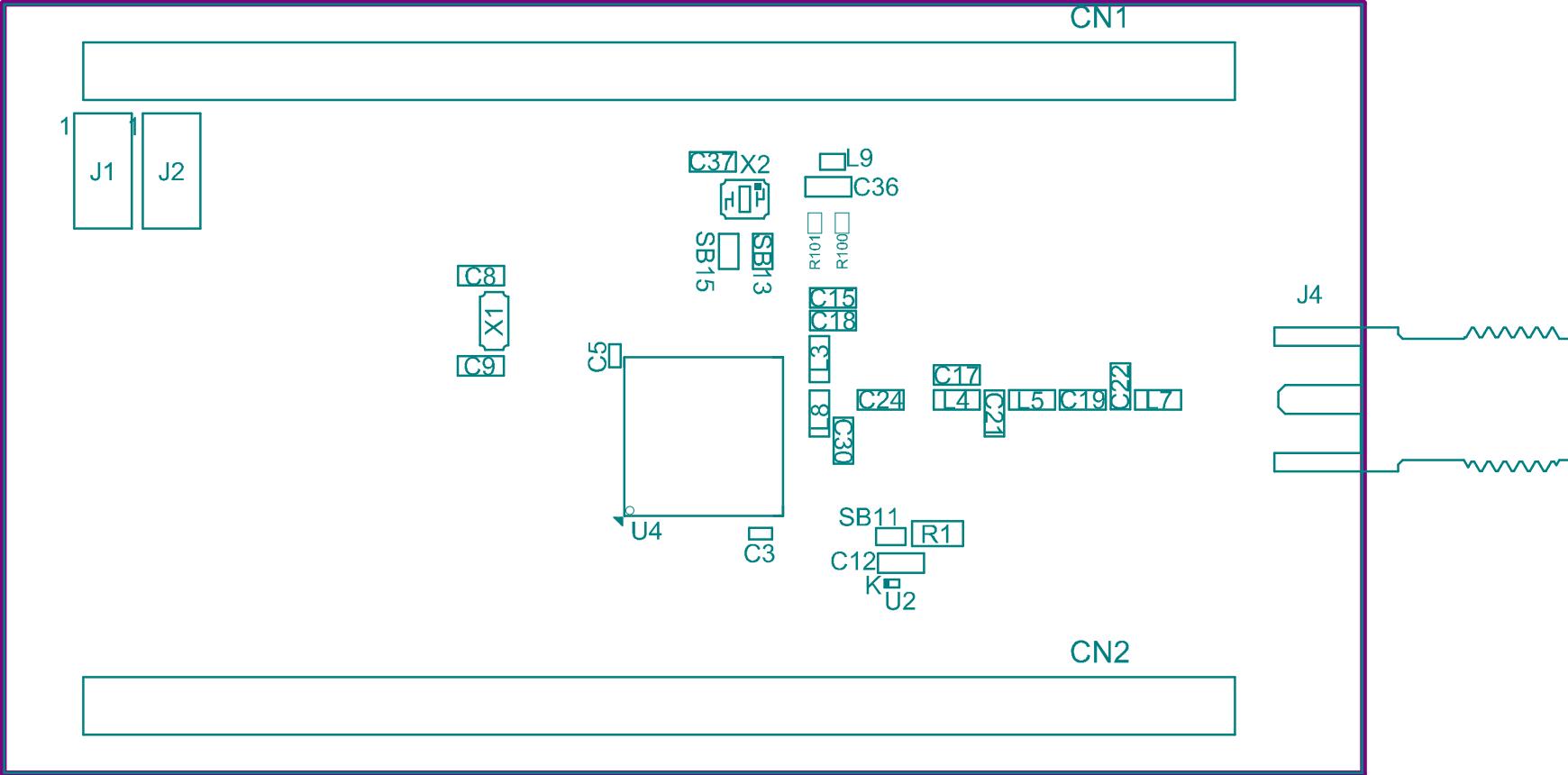
U_Top
MB1789_HPP.SchDoc



Title: Schematic sheet title to update		
Project: STM32WL_QFN48_HP_DirectTie_RefBoard		
Variant: LowBand_HighPower		
Revision: A-01	Reference: MB1789_HPP	
Size: A4	Date: 04-04-2022	Sheet: 1 of 2







Project: STM32WL_QFN48_HP_DirectTie_RefBoard

Layer: Top Assembly

Gerber: .GM14

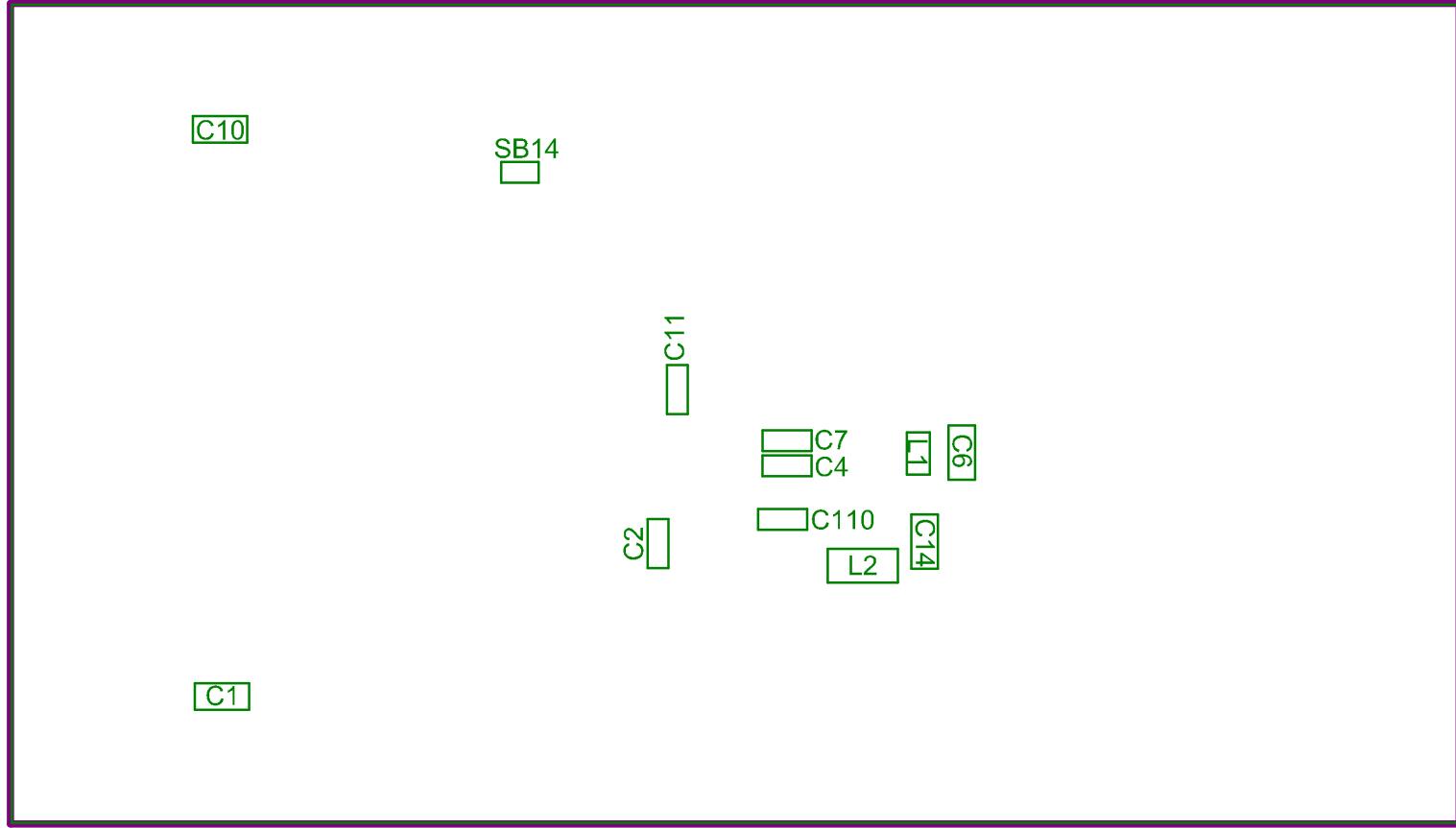
Variant: LowBand_HighPower

Ref: MB1789_HP

Date: 04-04-2022

Rev: A





Project: STM32WL_QFN48_HP_DirectTie_RefBoard

Layer: Bottom Assembly

Gerber:.GM15

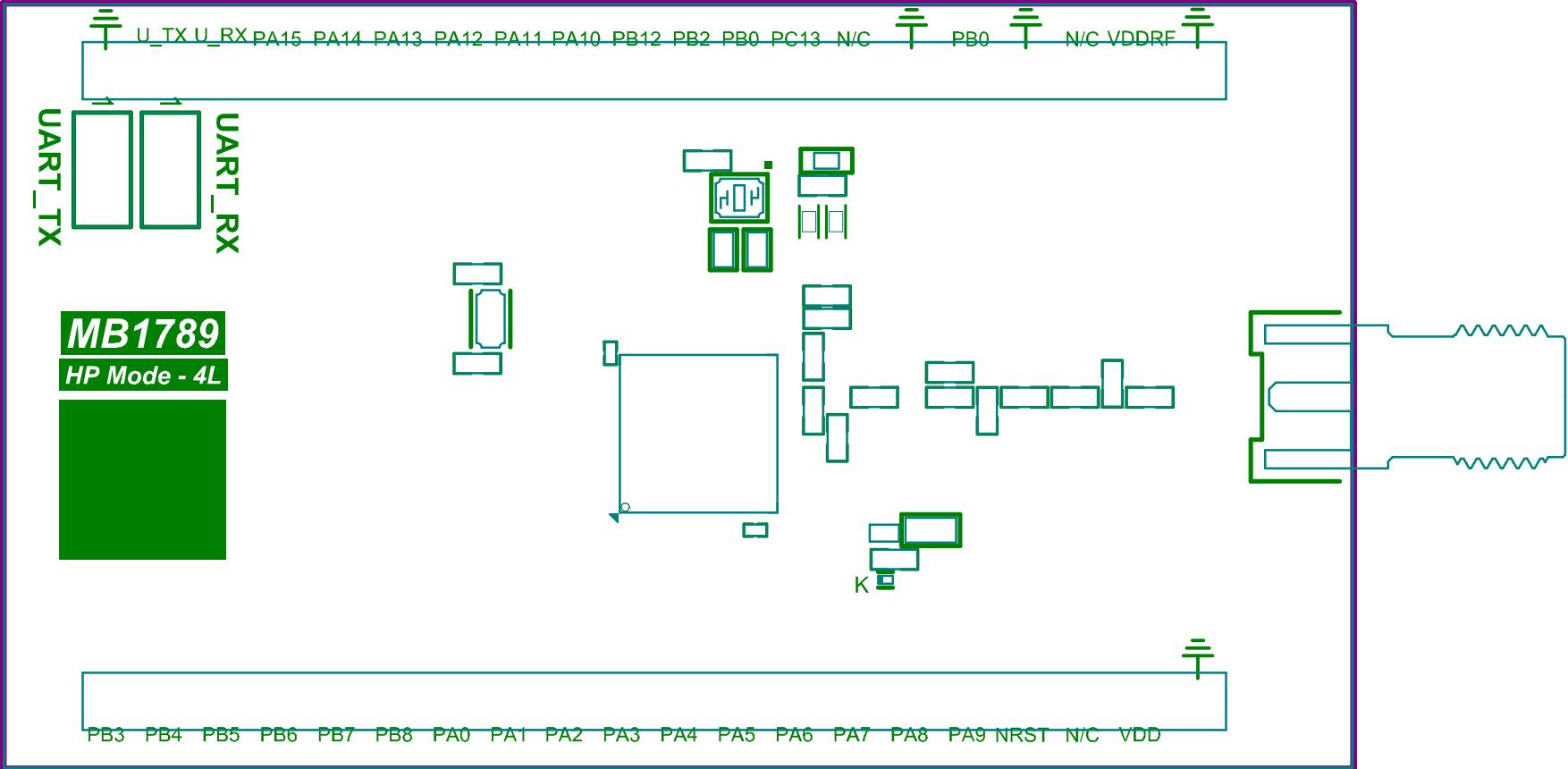
Variant: LowBand_HighPower

Ref: MB1789_HP

Date: 04-04-2022

Rev: A

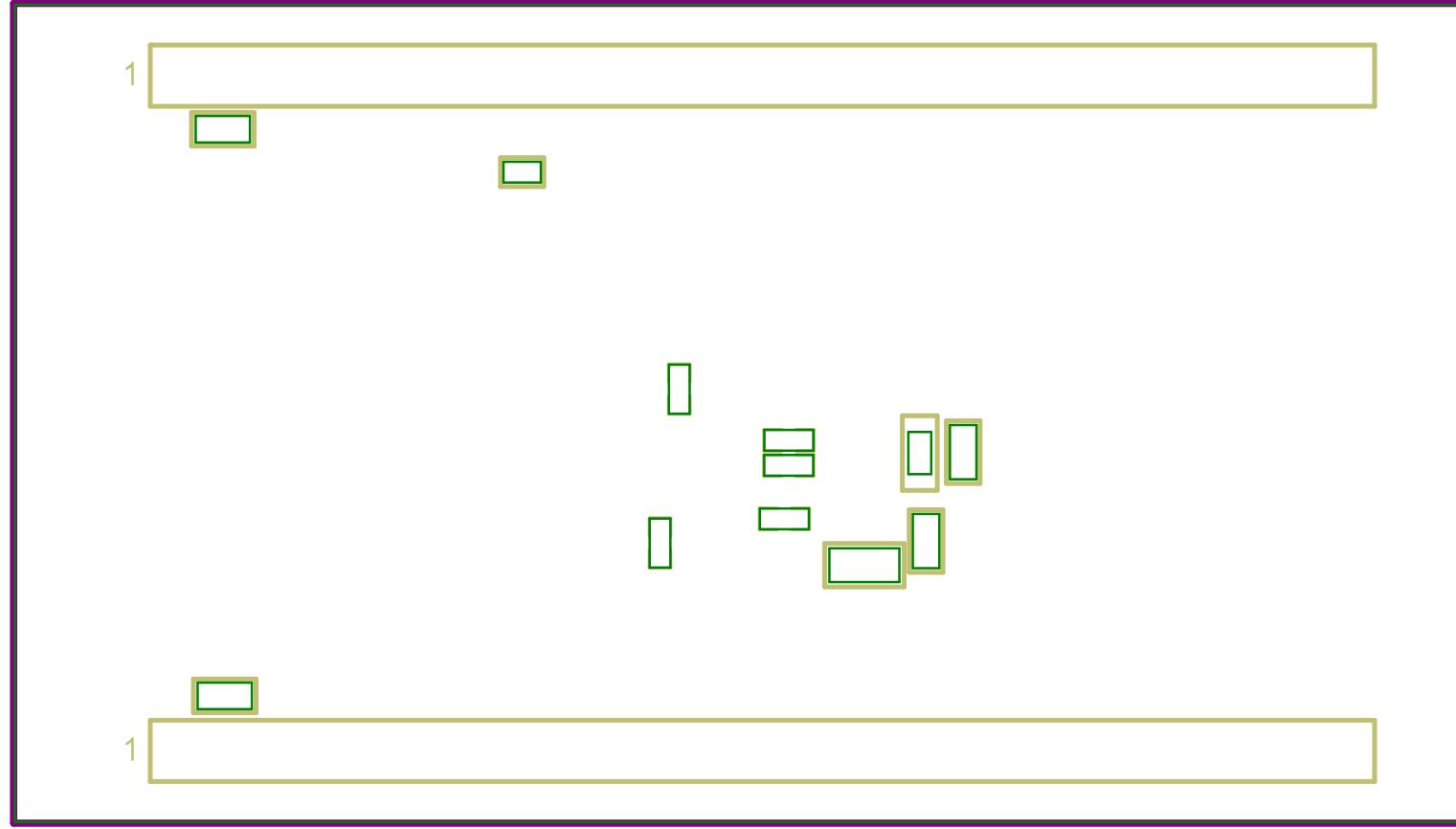




Top Overlay

.GTO

Bottom Overlay



.GBO